

FOR IMMEDIATE RELEASE
October 1, 2008



Jim Mundell

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New strategic business unit focuses on telecommunications and photonics markets...

NEXTREME APPOINTS MUNDELL HEAD OF TELECOM-FOCUSED THERMAL MANAGEMENT PRODUCTS BUSINESS UNIT

DURHAM, N.C. (October 1, 2008) — Nextreme Thermal Solutions, the leader in microscale thermal and power management products for the electronics industry, has appointed Jim Mundell to the position of Senior Vice President & General Manager of the newly created thermal management products business unit. The move signals Nextreme's intention to focus on its thermal management products and to aggressively engage with the telecommunications and photonics markets to enable the integration of its thin-film thermoelectric OptoCooler™ product line into optoelectronic devices.

Smaller packaging and higher heat densities can directly affect the performance and longevity of today's optoelectronics. Nextreme's products act as solid-state heat pumps and add thermal management functionality directly into the package to maintain the device's temperature at optimal conditions.

As Senior Vice President & GM at Nextreme, Mr. Mundell will be responsible for all aspects of the company's thermal management products business unit. Mundell has more than 30 years of experience in managing and growing high tech businesses in small and large companies. He most recently served as Nextreme's Chief Operating Officer and was responsible for transitioning Nextreme's technology from research to product.

Prior to joining Nextreme, Mr. Mundell has served in executive level management positions at General Electric, Harris Corporation, SCI Systems, and CTS Corporation covering the semiconductor, microelectronic, and electronic manufacturing services businesses. Additionally, he has over 15 years of experience in managing and growing start-up companies.

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"As an initial target, the telecommunications and photonics markets represent a large opportunity for Nextreme," said Mundell. "The size, efficiency and power-pumping capability of our thermoelectric product line make them ideally suited for optoelectronic applications. We are also seeing a lot of interest for microscale thermal management in other markets including computing, mobile and consumer product applications."

Mr. Mundell is a graduate of Purdue University where he received his BS in Electrical Engineering Technology and his MBA. Jim and his family have been located in Raleigh since 1986.

Nextreme's unique thin-film thermoelectric products are manufactured in volume with the Copper Pillar Bump process, an established electronic packaging approach that scales well into large arrays. The Thermal Copper Pillar Bump process integrates thin-film thermoelectric material into the solder bumped interconnects that provide mechanical and electrical connections for today's high performance/high density integrated circuits.

For more information, contact Nextreme at 3908 Patriot Dr., Suite 140, Durham, NC 27703-8031; call (919)-597-7300; e-mail info@nextreme.com; or go to www.nextreme.com.

About Nextreme Thermal Solutions™, Inc.

Nextreme Thermal Solutions designs and manufactures microscale thermal and power management products for the electronics, telecommunications, semiconductor, consumer, and defense/aerospace industries. The company uses breakthrough thin-film thermoelectric material to embed cooling, temperature control and power generation capabilities into the widely accepted copper pillar bumping process used in high-volume electronic packaging. Nextreme's headquarters and manufacturing facility are based near Research Triangle Park, North Carolina.

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